

In re Application of:

Kevin M. McHugh

Serial No.: 09/592,003

Filed: June 12, 2000

For: RAPID SOLIDIFICATION

PROCESSING FOR PRODUCING MOLDS,

DIES AND RELATED TOOLINGS

Examiner: Leyson

Group Art Unit: 1722

Attorney Docket No.: EGG-PI-612A1a

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CERTIFICATE OF MAILING

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AMENDMENT

Commissioner for Patents and Trademaks P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated May 7, 2003 please amend the above-referenced patent application as follows:

Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.